

FIG. 1A

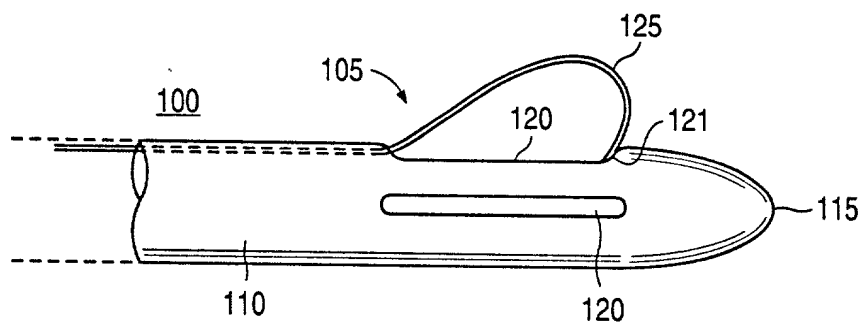


FIG. 1B

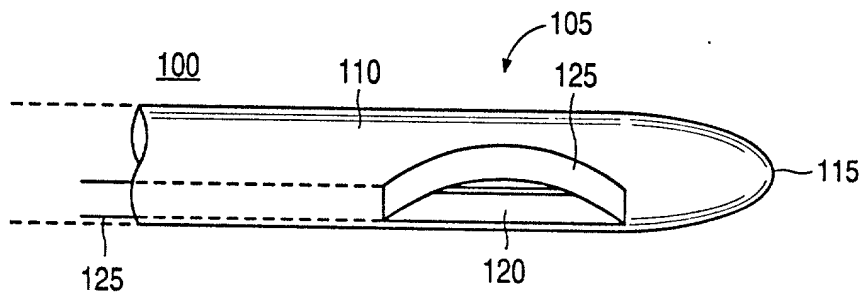


FIG. 1C

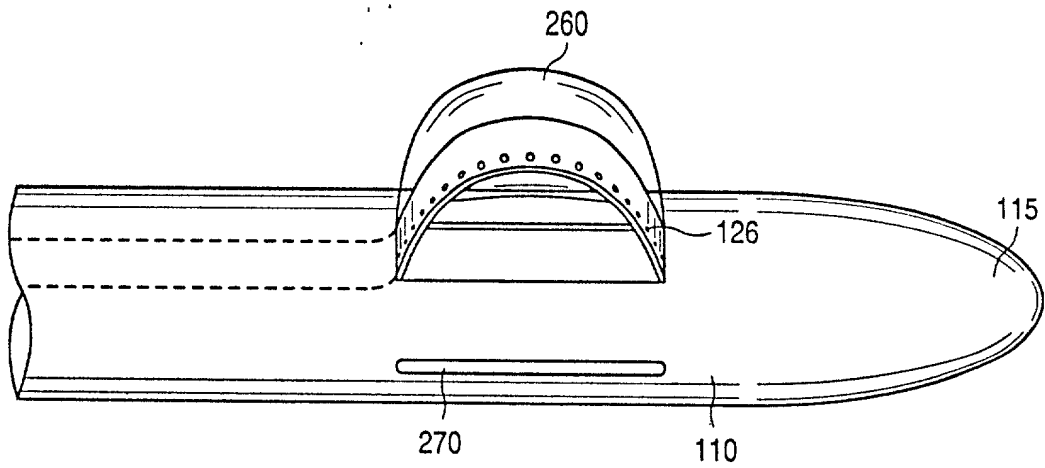


FIG. 2A

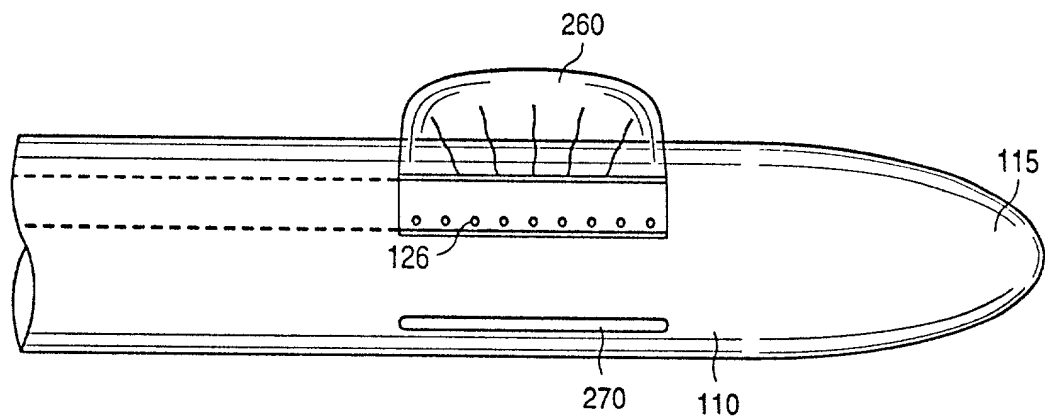


FIG. 2B

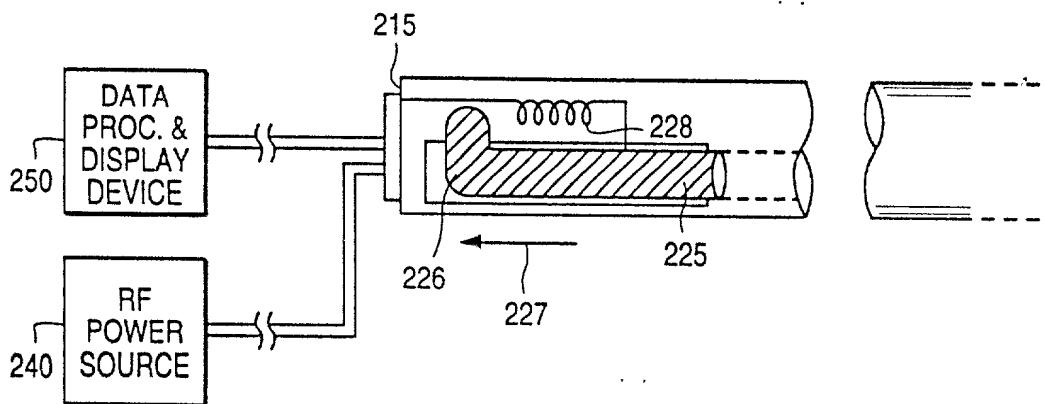
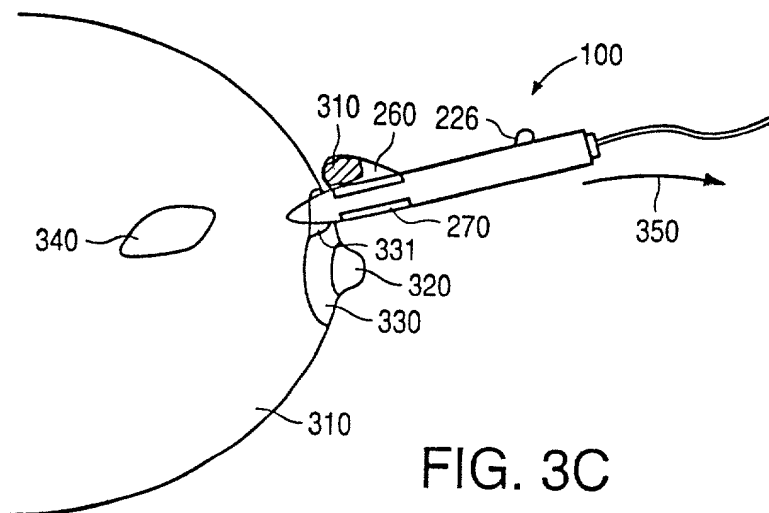
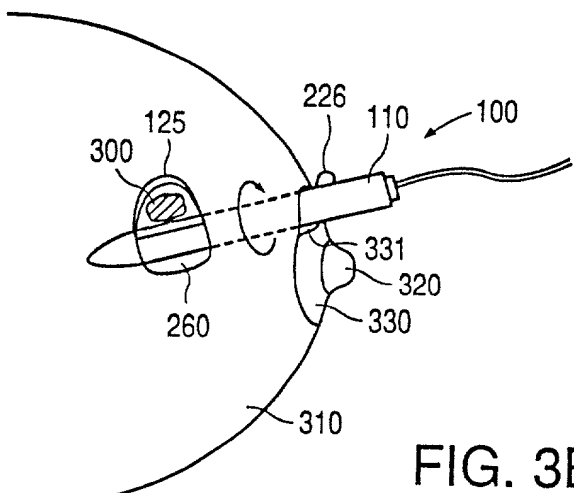
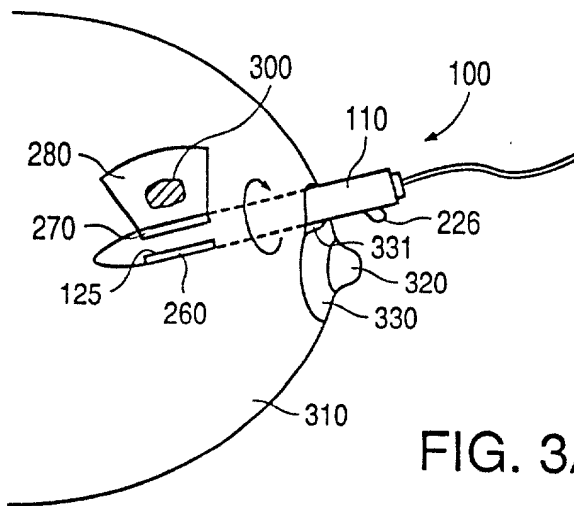


FIG. 2C



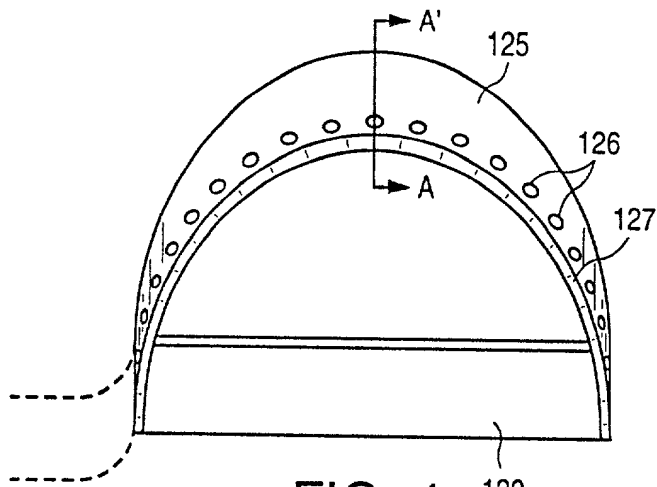


FIG. 4

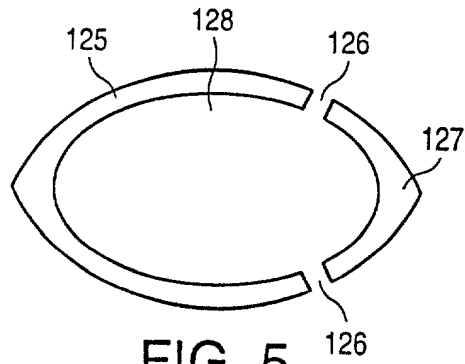


FIG. 5

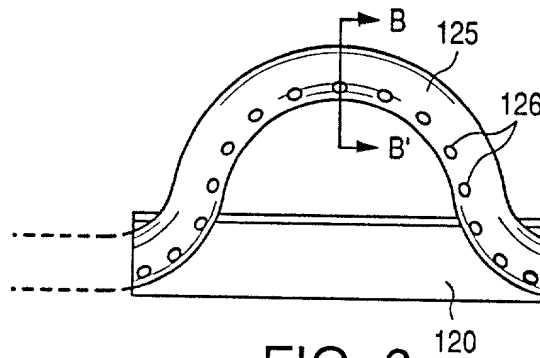


FIG. 6

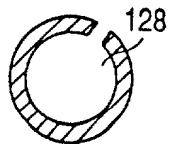


FIG. 7

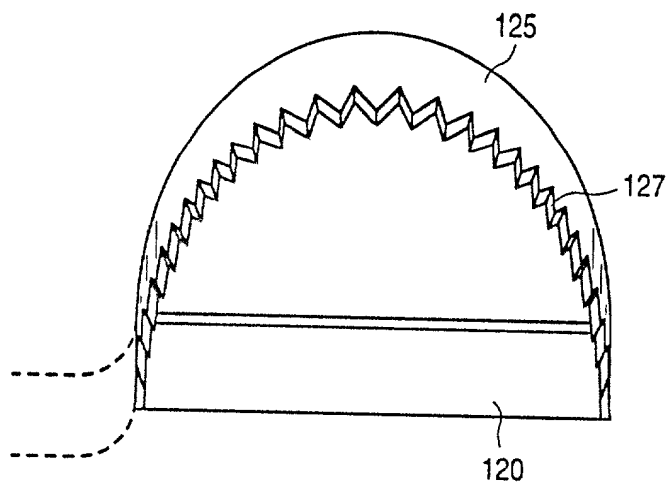


FIG. 8

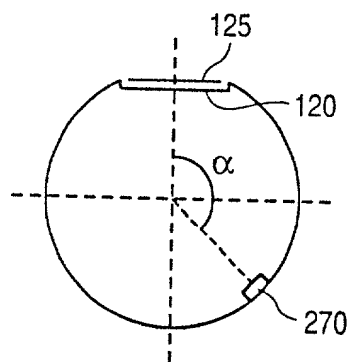


FIG. 9

FIG. 10 is a cross-sectional view of the device 100 taken along line A-A' of FIG. 11. The device 100 includes a main body 110, a first layer 120, a second layer 125, and a third layer 131. A series of small circles 115 are located between the first and second layers. A dashed line 116 indicates a boundary or interface. A cross-section A-A' is shown, and a component 410 is visible within the main body.

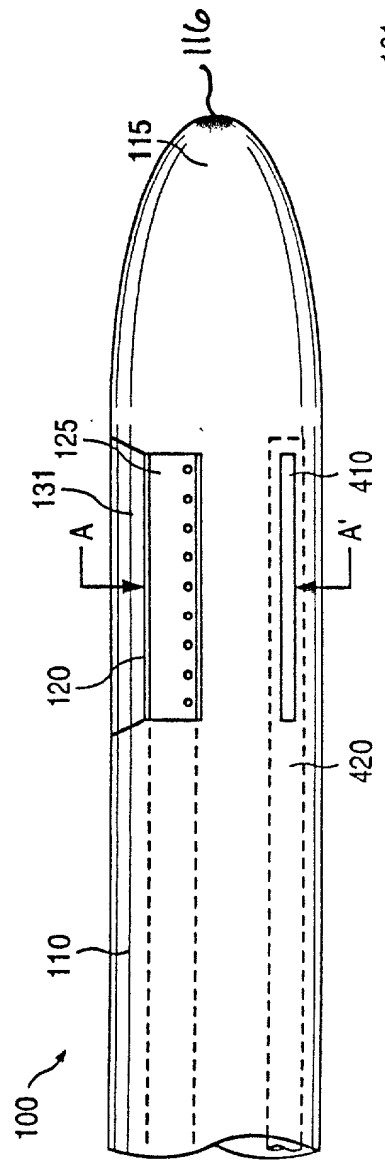


FIG. 10

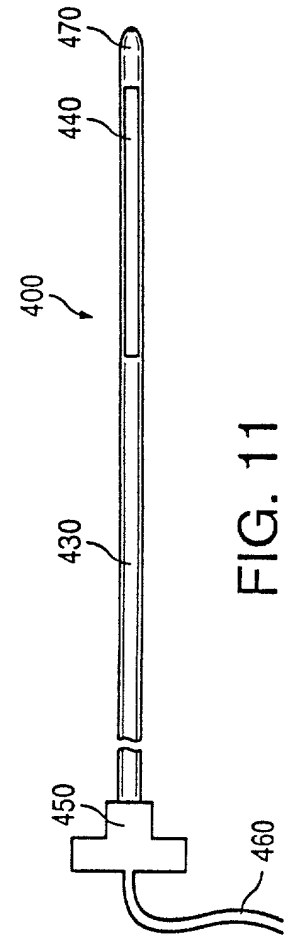


FIG. 11

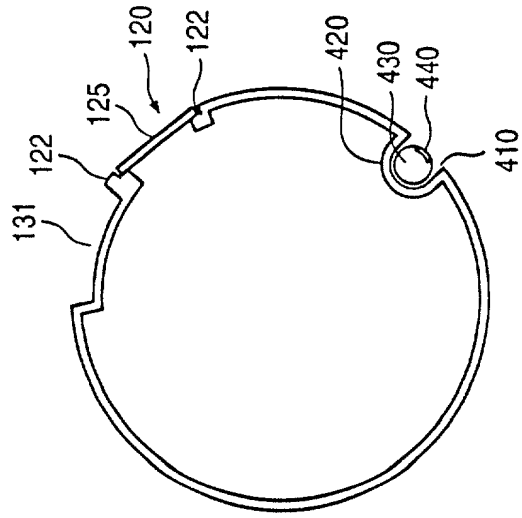


FIG. 12

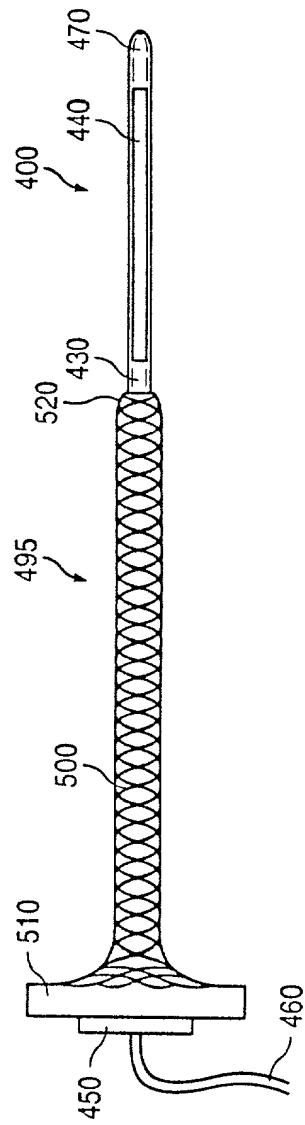


FIG. 13

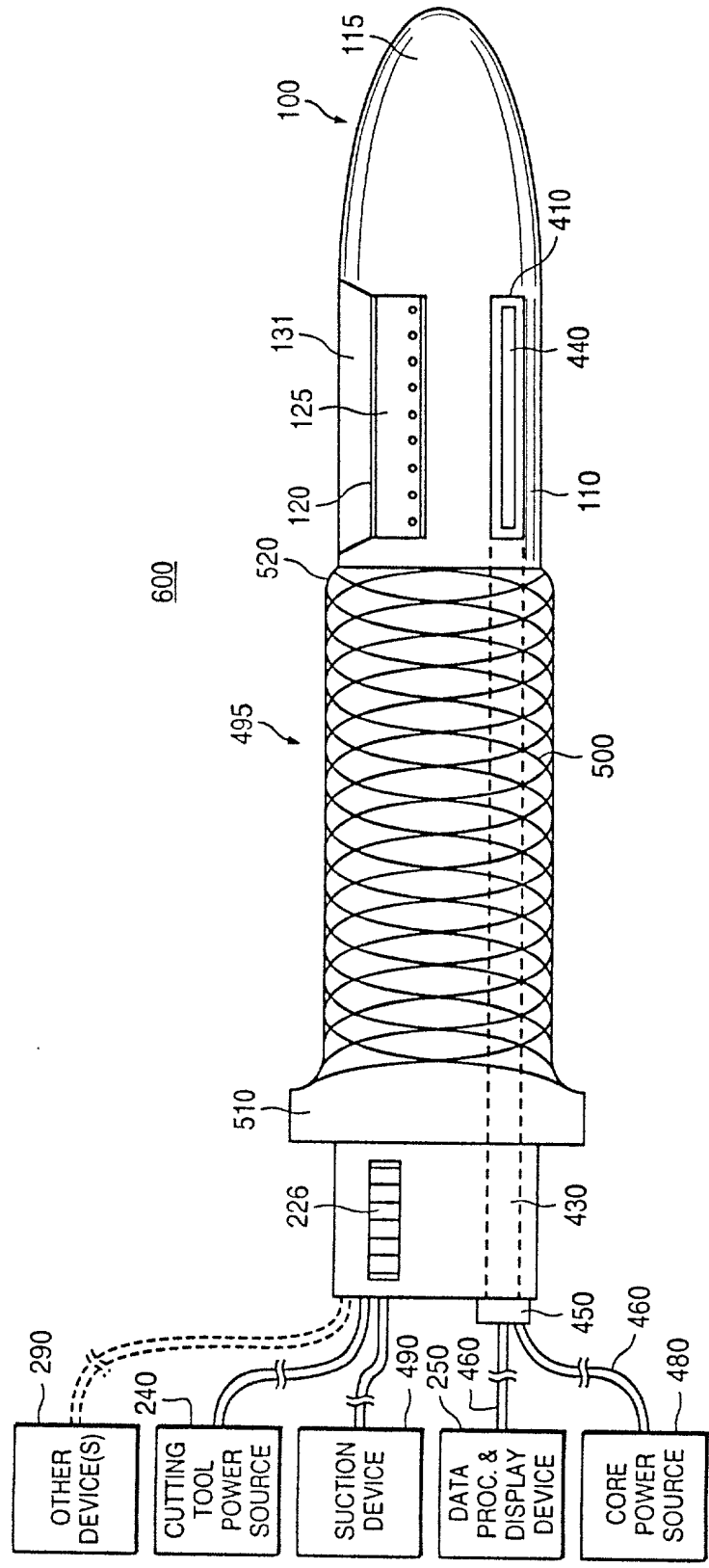


FIG. 14

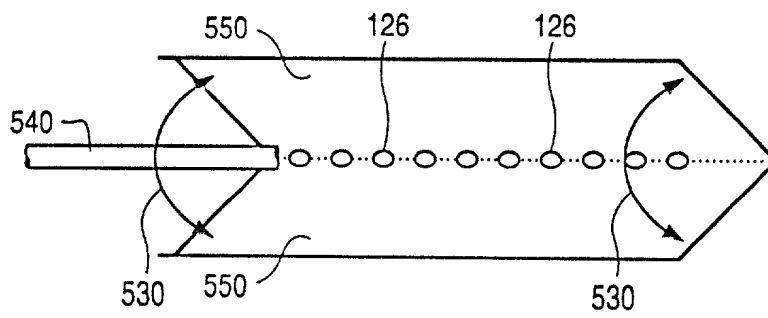


FIG. 15

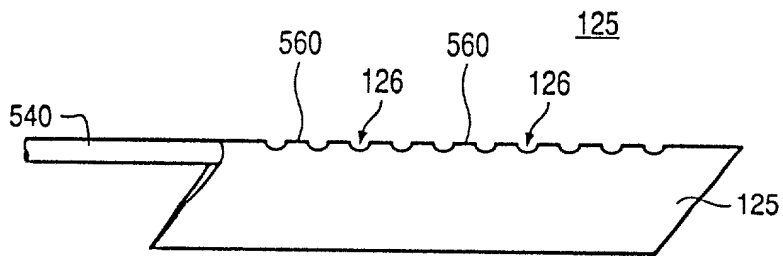


FIG. 16

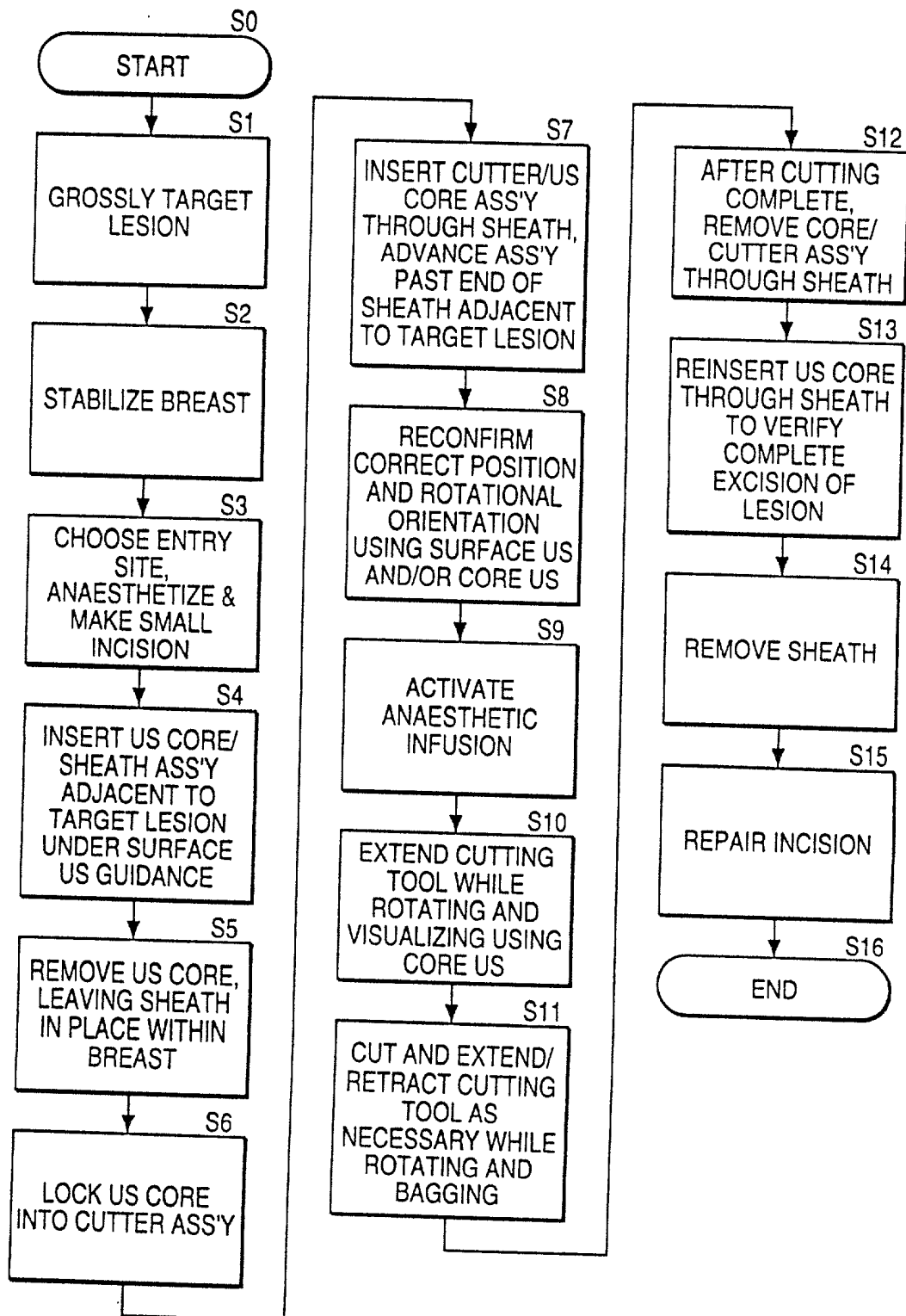


FIG. 17

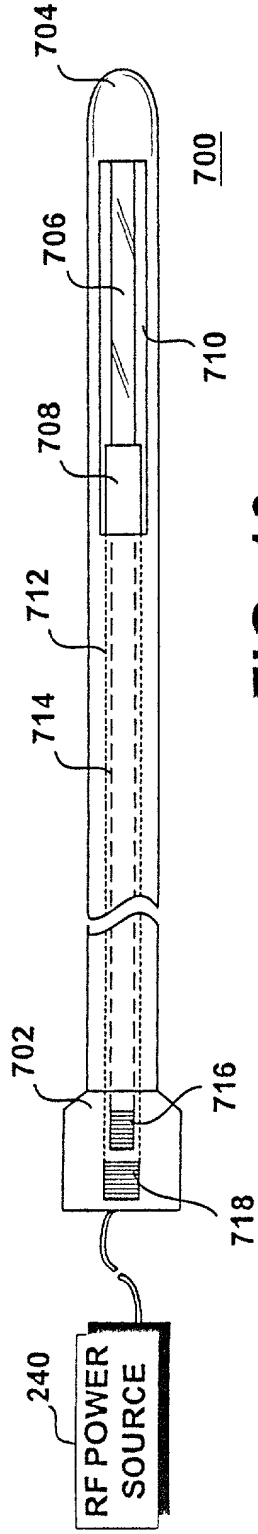


FIG. 18

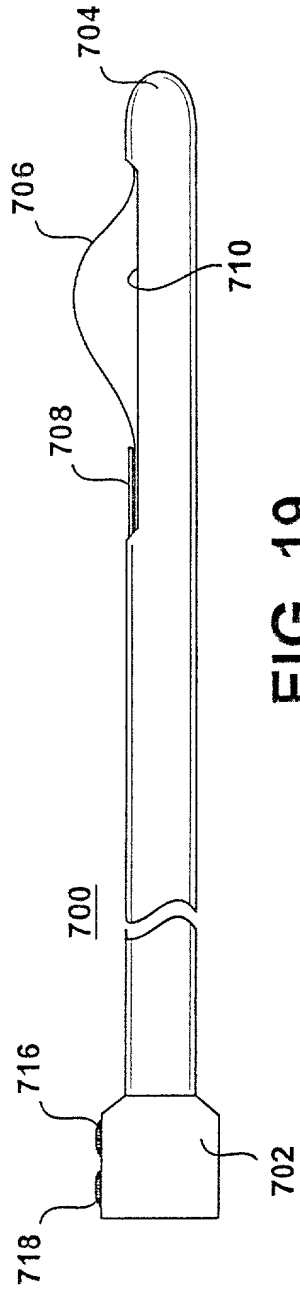


FIG. 19

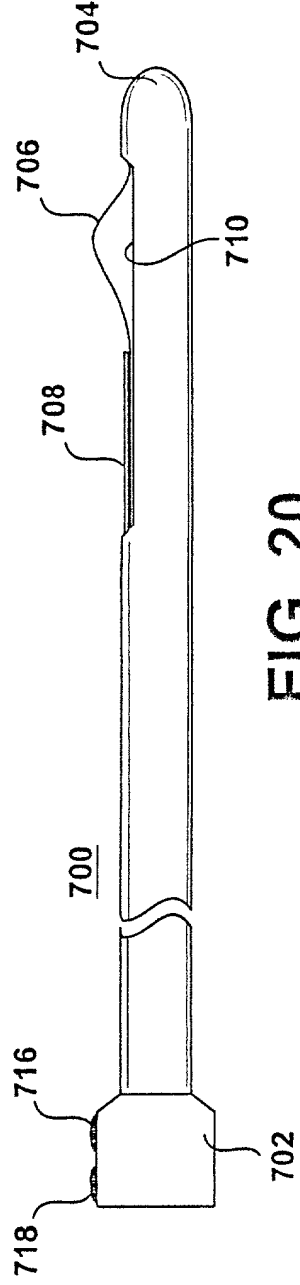


FIG. 20

FIG. 21

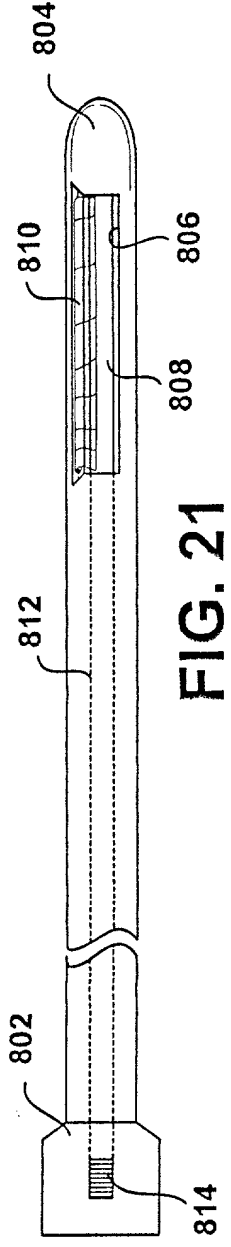


FIG. 21

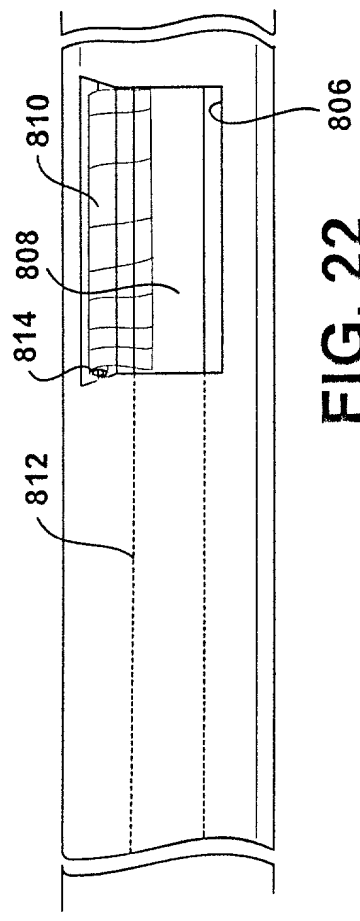


FIG. 22

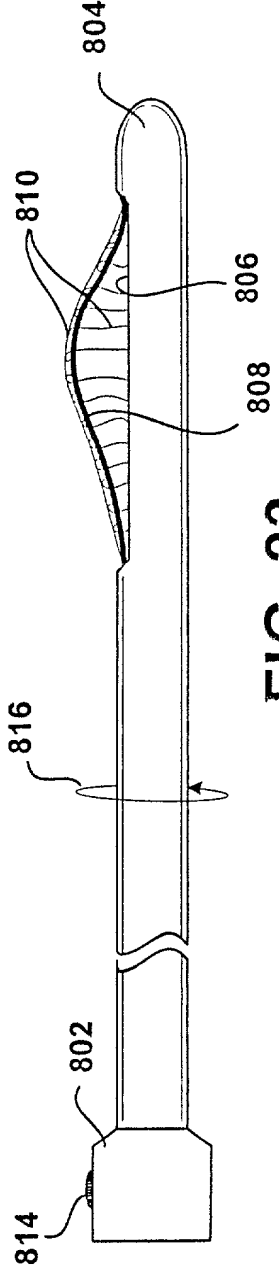


FIG. 23

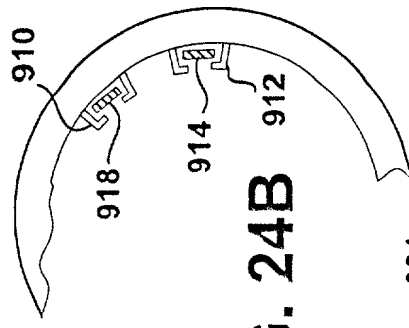


FIG. 24B

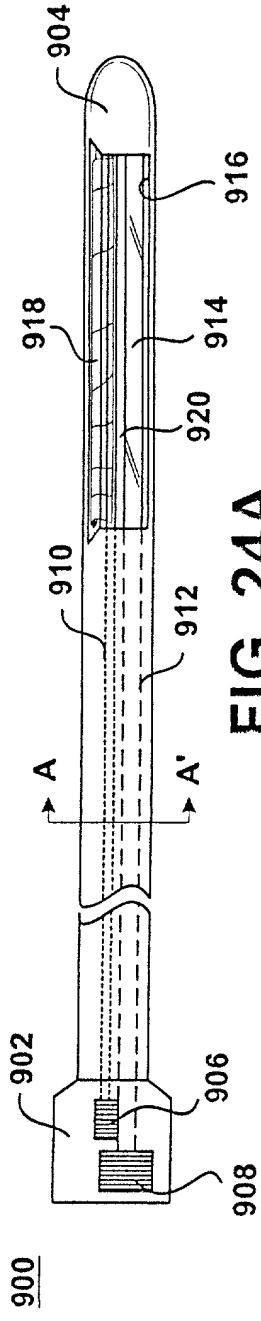


FIG. 24A

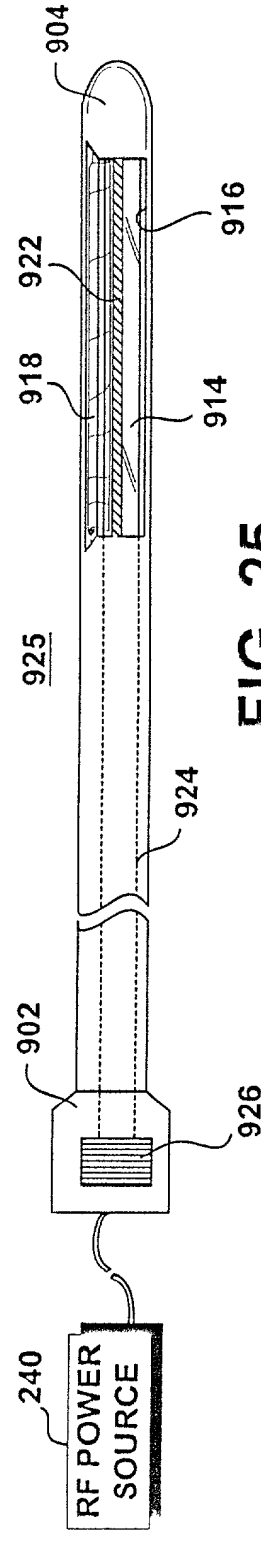


FIG. 25

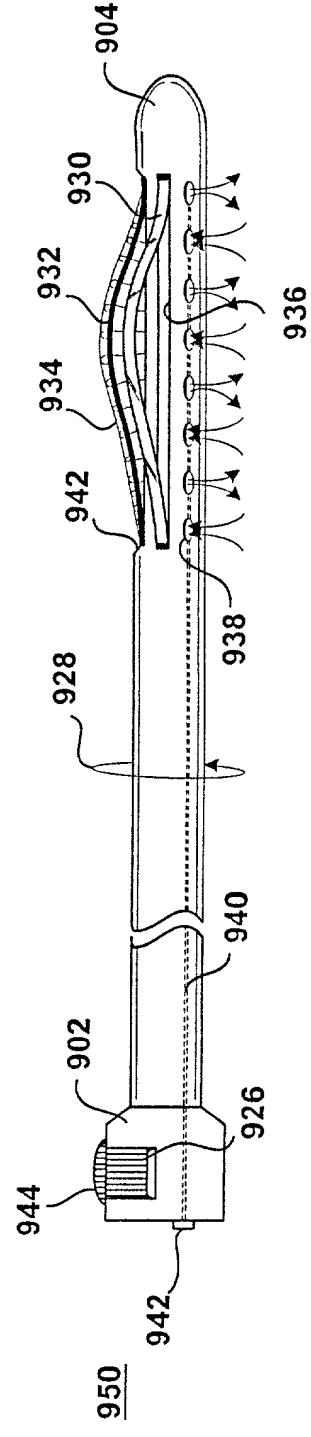


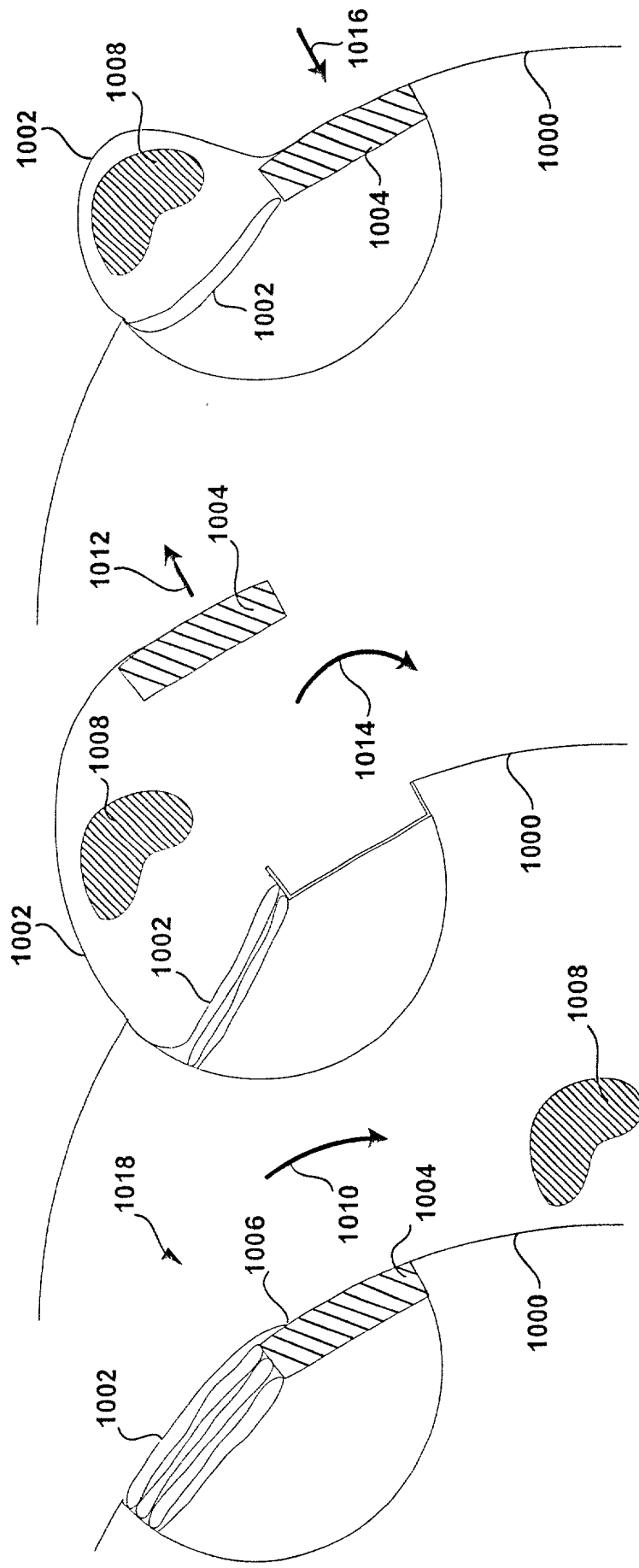
FIG. 26

RF POWER SOURCE

FIG. 27A

FIG. 27B

FIG. 27C



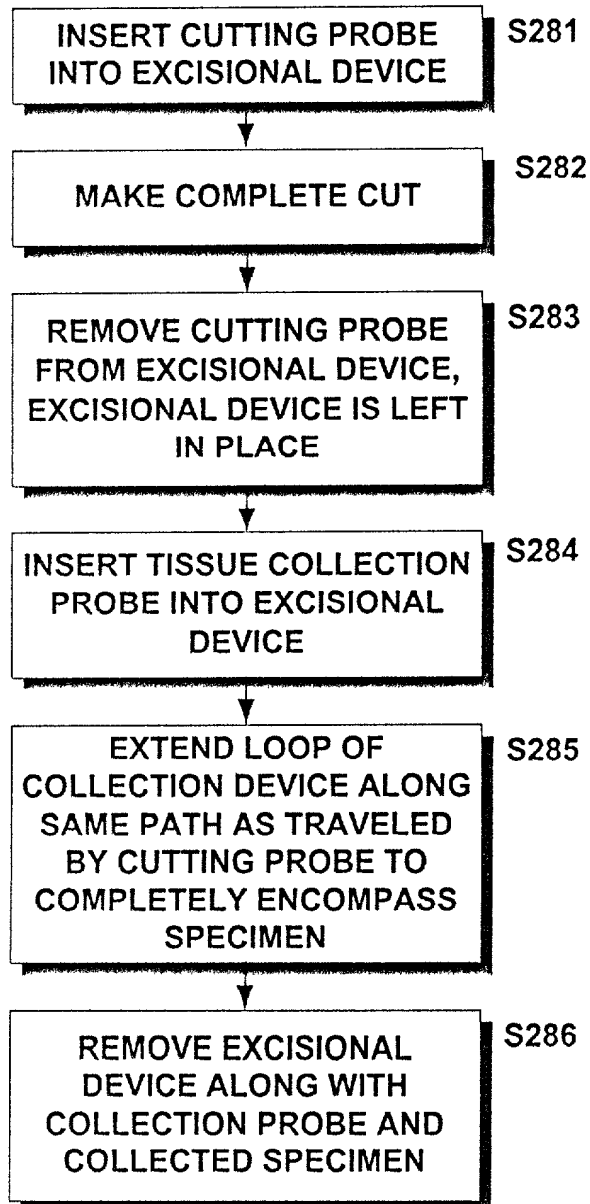


FIG. 28